Title (en)

ELECTRONIC ASSEMBLY

Title (de)

ELEKTRONISCHE ANORDNUNG

Title (fr)

DISPOSITIF ÉLECTRONIQUE

Publication

EP 4173452 A2 20230503 (DE)

Application

EP 21733075 A 20210609

Priority

- DE 102020207871 A 20200625
- EP 2021065465 W 20210609

Abstract (en)

[origin: WO2021259639A2] The present invention relates to an electronic assembly (1) comprising: a base plate (2); an electronic component (3) having a plurality of pins (30) which each extend parallel to a press-in axis (4); a printed circuit board (5) which is pressed onto the pins (30) along the press-in axis (4); a cooling region (6) which is formed between the electronic component (3) and the base plate (2); and a sealing arrangement (7) which is located between the base plate (2) and the electronic component (3) and is designed to seal the cooling region (6), wherein the sealing arrangement (7) has a seal support (71) and at least one seal (72), the seal support (71) has a plurality of press-in domes (75) projecting parallel to the press-in axis (4), and the electronic component (3) is supported by means of the press-in domes (75) of the seal support (71) in order to absorb a press-on force (40) when the printed circuit board (5) is pressed onto the pins (30).

IPC 8 full level

H05K 5/00 (2006.01); **H01R 12/58** (2011.01)

CPC (source: EP US)

H05K 5/0069 (2013.01 - EP US); **H05K 7/20845** (2013.01 - US); H01R 12/58 (2013.01 - US); H01R 12/585 (2013.01 - EP)

Citation (search report)

See references of WO 2021259639A2

Designated contracting state (EPC)

AL AT BE BG CH CY CZ DE DK EE ES FI FR GB GR HR HU IE IS IT LI LT LU LV MC MK MT NL NO PL PT RO RS SE SI SK SM TR

Designated extension state (EPC)

BA ME

Designated validation state (EPC)

KH MA MD TN

DOCDB simple family (publication)

DE 102020207871 A1 20211230; CN 115804250 A 20230314; EP 4173452 A2 20230503; JP 2023531073 A 20230720; JP 7494330 B2 20240603; US 2023255004 A1 20230810; WO 2021259639 A2 20211230; WO 2021259639 A3 20220217

DOCDB simple family (application)

DE 102020207871 A 20200625; CN 202180044995 A 20210609; EP 2021065465 W 20210609; EP 21733075 A 20210609; JP 2022580140 A 20210609; US 202118013084 A 20210609